



CONNECTING
People and Technology

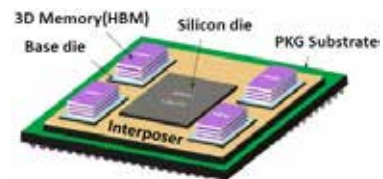
Start Your HBM/2.5D Design Today Webinar

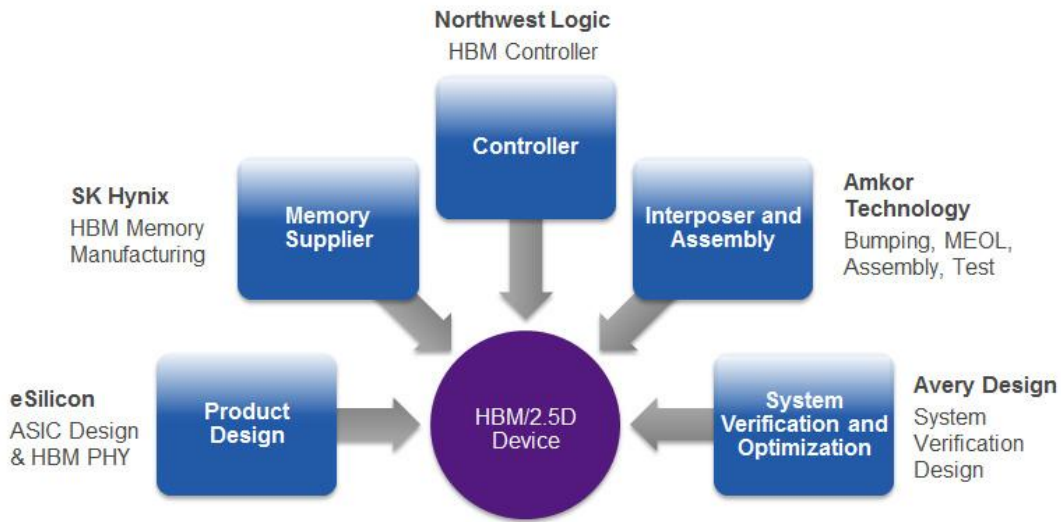
March 29, 2016 | Online Webinar

SK hynix, Inc., Amkor Technology, eSilicon, Northwest Logic and Avery Design Systems have joined forces to offer a complete High Bandwidth Memory (HBM) supply chain solution. HBM is a JEDEC-defined standard that utilizes 2.5D technology to interconnect a SoC and a HBM memory stack. Many companies are already using HBM to create very high-bandwidth, low-power products. This seminar will present a complete HBM supply chain that is delivering and supporting customer HBM designs now. Webinar attendees will also receive a white paper on the development and implementation of HBM designs.

Tuesday, March 29, 2016
8:00 AM & 6:00 PM
Pacific time

[Register](#)





Agenda

Speaker



3D Memory Stack

Kevin Tran, Senior Manager,
Technical Marketing



Interposer & Assembly

Paul Silvestri, Director of TSV
Product Development



2.5D Package, Silicon
Die & HBM PHY

Bill Isaacson, Director, ASIC
Product Marketing



HBM Controller

Brian Daellenbach, President



System Verification &
Optimization

Chris Browy, Senior VP, WW
Sales and Marketing

[Register](#)

Join Us For These Upcoming Events

Mark your calendars and join Amkor at the following events.

- 05/11/16 | [14th Annual MEPTEC MEMS Technology Symposium](#)
- 05/17/16 | [TSMC China Technology Symposium](#)
- 05/26/16 | [TSMC Taiwan Technology Symposium](#)
- 05/31/16 | [ECTC - IEEE/CMPT 65th Electronics Components and Technology Conference](#)

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